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(54) Title: METHOD AND SYSTEM FOR MANUFACTURING INTEGRATED FLUIDIC CHIPS

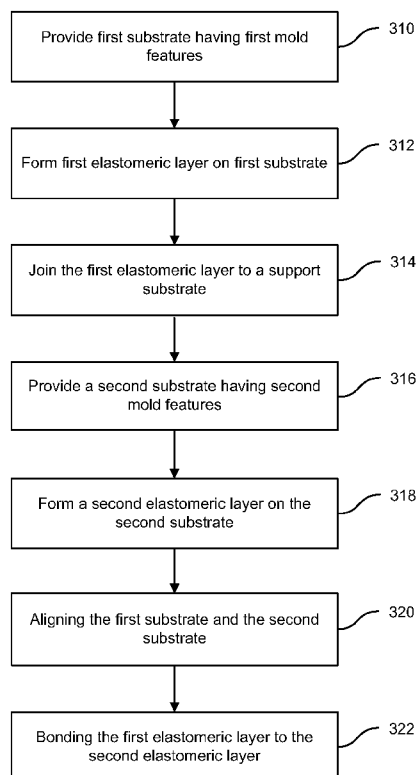


FIG. 3

(57) Abstract: METHOD AND SYSTEM FOR MANUFACTURING INTEGRATED FLUIDIC CHIPS ABSTRACT OF THE DISCLOSURE An integrated fluidic chip includes a substrate defined by a lateral surface area greater than 28 square inches. The integrated fluidic chip also includes a first elastomeric layer having a mold surface and a top surface. The mold surface of the first elastomeric layer is joined to a portion of the substrate. The first elastomeric layer includes a plurality of first channels extending normally from the substrate to a first dimension inside the first elastomeric layer. The integrated fluidic chip further includes a second elastomeric layer having a mold surface and a top surface. The mold surface of the second elastomeric layer is joined to at least a portion of the top surface of the first elastomeric layer.



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